



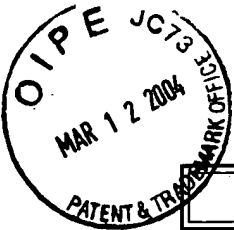
Electronic Filing System (EFS) Data  
Electronic Patent Application Submission  
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EFS ID: 57017  
Application ID: 10706468  
Title of Invention: SEMICONDUCTOR PACKAGE  
WITH CHAMFERED CORNERS  
AND METHOD OF  
MANUFACTURING THE SAME  
First Named Inventor: Sung Yang  
Domestic/Foreign Application: Domestic Application  
Filing Date: 2003-11-12  
Effective Receipt Date: 2004-03-12  
Submission Type: Information Disclosure  
Statement  
Filing Type:  
Confirmation number: 6744  
Attorney Docket Number: AMKOR095A



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Digital Certificate Holder: cn=Mark B. Garred,ou=Registered Attorneys,ou=Patent and Trademark  
Office,ou=Department of Commerce,o=U.S. Government,c=US  
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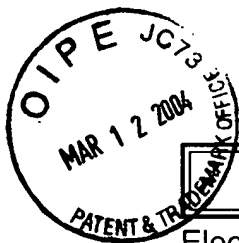


# TRANSMITTAL

Electronic Version v1.1

Stylesheet Version v1.1.0

Title of Invention	SEMICONDUCTOR PACKAGE WITH CHAMFERED CORNERS AND METHOD OF MANUFACTURING THE SAME									
Application Number: 10/706468 										
Date: 2003-11-12										
First Named Applicant: Sung Jin Yang										
Confirmation Number: 6744										
Attorney Docket Number: AMKOR095A										
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Mark B. Garred Registered Number: 34,823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	Mark B. Garred Registered Number: 34,823	/mbg/	Attorney		
Submitted by:	Elec. Sign.	Sign. Capacity								
Mark B. Garred Registered Number: 34,823	/mbg/	Attorney								
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	us-ids.dtd									
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Comments										



# ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of  
Invention

SEMICONDUCTOR PACKAGE WITH CHAMFERED  
CORNERS AND METHOD OF MANUFACTURING THE  
SAME

Application Number: 10/706468  
Confirmation Number: 6744  
First Named Applicant: Sung Yang  
Attorney Docket Number: AMKOR095A  
Art Unit: 2811

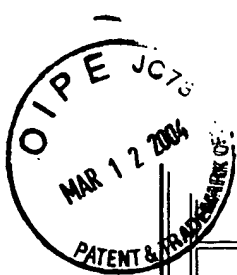


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or 5886398 or 5886397 or 5894108 or 5897339  
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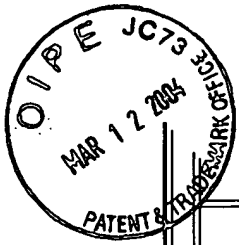
## US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

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	50	5903050	1999-05-11	THURAIRAJARATNAM ET AL.

Signature

Examiner Name	Date